

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6	(partition or wall) and circuit adj blocks and (first and second) adj sealing adj members	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2009/10/21 20:23
S2	54	(partition) and blocks and (first and second) adj sealing adj members	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2009/10/21 20:24
S3	14	circuit adj blocks and (first and second) adj sealing adj members	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2009/10/21 20:27
S4	37	("20020011907" "20020051340" "20020053127" "20020080593" "20020111015" "20020126018" "20020168798" "20030090883" "20040070083" "20040160752" "20040178495" "20040226744" "20040232452" "20040252475" "20050001331" "20050017740" "20050088260" "20060158865" "20060258050" "20070052091" "4547310" "4691434" "5480840" "5796164" "5907477" "6049468" "6093584" "6380491" "6472598" "6686649" "6734542" "6815810" "6884938" "7049682" "7402502" "7449412" "7478474").PN.	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2009/10/21 20:30

S5	77416	(partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or dielectric or insulat\$3 or encapsulat\$3 or top or cap) and (foil or (metal or conduct\$3) adj (layer or film))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/10/21 22:27
S6	77416	(partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or dielectric or insulat\$3 or encapsulat\$3 or top or cap) and (foil or (metal or conduct\$3) adj (layer or film))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:27
S7	373	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or dielectric or insulat\$3 or encapsulat\$3 or top or cap) and (foil or (metal or conduct\$3) adj (layer or film))). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:28

S8	11	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or dielectric or insulat\$3 or encapsulat\$3 or top or cap) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film))). cfm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:39
S9	1776	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or dielectric or insulat\$3 or encapsulat\$3 or top or cap) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:41
S10	368	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:42

S11	18	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:43
S12	13276	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (foil or (metal or conduct\$3) adj (layer or film)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:45
S13	16	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (foil or (metal or conduct\$3) adj (layer or film))and	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:46

		(component or die or chip)adj module)				
S14	16	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)adj module)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:48
S15	55	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)adj module)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:49
S16	0	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:53

		polyester) same (conduct\$3 and (first and second) near (foil or (metal or conduct\$3) adj (layer or film))). c1m.				
S17	0	((partition\$3 or block or wall or dam or support) and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)adj module)).c1m.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2009/10/21 22:54
S18	274	257/795.ccls.	US-PGPUB; USPAT; USOCR; FPRS	OR	ON	2009/10/21 23:11

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	85	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same ((resin or plastic or epoxy or polymer or polyamide or polyester)same conduct\$3 or metal near fill\$3) and (substrate or board or base or carrier) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film)))and 257/659,660,795.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:37

L2	151	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same ((resin or plastic or epoxy or polymer or polyamide or polyester)same conduct\$3 or metal near fill\$3) and (substrate or board or base or carrier) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))))and 257/e23.114.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:43
L3	14	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same ((ceramic near (powder or filler))same conduct \$3 or metal near fill\$3)and (substrate or board or base or carrier) same (ceramic) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))))and 257/e23.114.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:53
L4	2	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same ((ceramic near (powder or filler))same conduct \$3 or metal near fill\$3)and (substrate or board or base or carrier) same (ceramic) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))))and 257/659,660,795.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:55

L5	1	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same ((ceramic near (powder or filler))same conduct\$3 or metal near fill\$3)and (substrate or board or base or carrier) same (ceramic) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))).clm.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:56
L6	13	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same ((resin or plastic or epoxy or polymer or polyamide or polyester)same (conduct\$3 or metal) near fill \$3)and (substrate or board or base or carrier) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film)))and 257/e23.114.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:57
L7	8	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same ((resin or plastic or epoxy or polymer or polyamide or polyester)same (conduct\$3 or metal) near fill \$3)and (substrate or board or base or carrier) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:58

		((layer or film)))and 257/659,660,795.ccls.				
L8	5	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same (resin or plastic or epoxy or polymer or polyamide or polyester)same (conduct\$3 or metal) near fill \$3)and (substrate or board or base or carrier) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))).clm.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 14:58
S19	0	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film))).clm.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/21 22:53
S20	0	((((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)adj module)).clm.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/21 22:54

S21	5	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)adj module))and 257/659,660,690,790.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 22:54
S22	0	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)adj module))and 29/841.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 22:55
S23	2	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)))and 29/841.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 22:56
S24	13	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)))and 257/659,660,690,790.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 22:56

S25	156	((partition\$3 or block or wall or dam or support)and (substrate) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (circuit adj block) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) and (ground or foil or (metal or conduct\$3) adj (layer or film))and (component or die or chip)))and 257/659-790.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 22:58
S26	4	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film)))and 257/659-790.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:02
S27	0	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film)))and 174/527,535.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:03

S28	0	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film))))and 29/841.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:04
S29	0	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (ceramic) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film))))and 29/841.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:05
S30	2	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) same (ceramic) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film))))and 257/659-790.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:05

S31	2	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) and(ceramic) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film)))and 257/659-790.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:06
S32	0	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) and(ceramic) and (component or die or circuit adj block or chip) and (first and second) near(seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (foil or (metal or conduct\$3) adj (layer or film)))and 257/795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:10
S33	15	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (foil or (metal or conduct \$3) adj (layer or film)))and 257/795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/21 23:10
S34	153	((partition\$3 or block or wall or dam adj structure or support adj frame)and (substrate or board or base) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (foil or (metal or conduct \$3) adj (layer or film)))and 257/E23.114.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:16

S36	0	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal \$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (ground or foil or (metal or conduct\$3) adj (layer or film))). clm.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:29
S37	0	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal \$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (ground or foil or (metal or conduct\$3) adj (layer or film)))) and 257/659,660,795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:30
S38	0	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal \$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (first and second) near (ground or foil or (metal or conduct\$3) adj (layer or film)))) and 257/E23.114.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:30

S39	6	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal \$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))) and 257/E23.114.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:31
S40	1	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second) near(seal \$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))) and 257/659,660,795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:31
S41	127	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3)and (substrate or board or base) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film)))and 257/659,660,795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:33

S45	139	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)and (substrate or board or base or carrier) same (resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3) same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))) and 257/659,660,795.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 10:48
S46	141	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)and (substrate or board or base or carrier) same (ceramic or resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))) and 257/659,660,795.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 11:03
S47	112	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same(resin or plastic or epoxy or polymer or polyamide or polyester) and (substrate or board or base or carrier) same (ceramic or resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film)))and 257/659,660,795.ccls.	US-PGPUB; USPAT; UPAD	AND	ON	2009/10/22 11:18

S48	1	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same(resin or plastic or epoxy or polymer or polyamide or polyester) and (substrate or board or base or carrier) same (ceramic or resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second)adj (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film)))and 257/659,660,795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 11:21
S49	1	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same(resin or plastic or epoxy or polymer or polyamide or polyester) and (substrate or board or base or carrier) same (ceramic or resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second)adj (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))) and 257/659,660,795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 11:22

S50	2	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same(resin or plastic or epoxy or polymer or polyamide or polyester) and (substrate or board or base or carrier) same (ceramic or resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second)adj (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3 or mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))) and 257/659,660,795.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 11:22
S51	3	((partition\$3 or block or wall or dam adj structure or support adj frame or shield\$3 or post or column)same(resin or plastic or epoxy or polymer or polyamide or polyester) and (substrate or board or base or carrier) same (ceramic or resin or plastic or epoxy or polymer or polyamide or polyester) and (component or die or circuit adj block or chip) and (first and second)adj (seal\$3 or encapsulat\$3 or top or cap or over\$mold\$3 or mold\$3)same (resin or polymer or plastic or epoxy or polyamide or polyester) same (conduct\$3) and (ground or foil or (metal or conduct\$3) adj (layer or film))) and 257/e23.114.ccls.	US- PGPUB; USPAT; UPAD	AND	ON	2009/10/22 11:23

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